



## QUALIFICATIONS

SC BLF03 is an RMA paste, which fulfils the demands of MIL-QQ-S571e. The corrosion-, solderballing-, wetting- and slump (SN 59650) tests have been passed. Laboratory tests certify non-corrosive residues, which can be left on the board, even under the protective coating, as the flux corresponds to RE L0 (no clean).

## STORAGE

Unopened at room temperature (20°C/68°F): 6 months

Open or on the printer squeegee the maximal processing time depends, of course, on the environmental influences on the paste. **A storage in the refrigerator is not necessary**, but a storage temperature of <22°C is recommended.

## APPLICATION INFORMATION

After using the paste close the container tightly.

Do not mix used and fresh paste, only to freshen up paste and only at work in progress.

Do not mix pastes of different kind.

Recommended squeegee speed: 15-100 mm/s.

For stencil printing, paste with 89% metal content is recommended.

Note: the printer is always faster than the fastest assembler in the production line.

The printer squeegee must be set to ensure that the paste performs a rolling action in front of the squeegee and does not slide!

The stencil can be washed with an alcohol mixture but the alcohol must not contaminate fresh paste. **We recommend the SC Stencil Cleaner**.

The paste is suitable for all common reflow systems.

## Solder Chemistry order example

Paste type	Alloy	Grain size	Flux content	Jar capacity
SC BLF03	96.5/3.0Ag/0.5Cu	T3	11%	500g
SC BLF03	96.5/3.5Ag	T3	11%	200g

Order example according to DIN:

Solder Paste(SC...) L-Sn96.5Ag3/Cu0.5 / 1.2.3.C / 89-3 200g(packing)

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